

# FVI360



大量科技  
TA LIANG

FVI360 is an excellent solution for semiconductor back end process. It offers flexible methods to detect different defects during the final visual inspection process.

## FEATURE



CHIP SIZE	0.5x0.5mm to 13x13mm
Carrier tape width	8mm, 12mm, 16mm, 24mm
Reel Diameter	7inch/13inch
All hot sealing & cold sealing cover tape White marking / Dark marking / Backside Coating Production	
Max UPH	60K(Max)
UPH	Die Size > 4x4mm:30K(Dual station) Die Size < 4x4mm:60K(Dual station)
Misjudgement rate (excluding external factors)	2%
Dimension(mm)	1576(L)*1776(H)*952(W)
Large sealing line Inspection	Option
SECS/GEM	Option
Reporting System (On server systems)	Option
Suspend if defect detection	Option
Auto labeling module	Option

